

Amendments to the Abstract:

Please add the Abstract of the Disclosure submitted herewith on a separate unnumbered page.

ABSTRACT

A multilayered module board with mounted high-frequency electronic components such as a CPU and a graphic circuit is mounted on one face of a base board with mounted low-frequency electronic components. The multilayered module board is a squared multilayered board smaller than the base board. The electronic components are wired with an inner layer-wiring pattern. Connector terminals are solder-jointed to four sides of the multilayered module board. The multilayered module board is mounted to the base board via the connector terminal.